

PATENT NUMBER

U.S. **UTILITY** Patent Application

M.S.

O.I.P.E.

PATENT DATE

SCANNED

Q.A

APPLICATION NO. 09/887104	CONT/PRIOR F	CLASS 91A	SUBCLASS 511	ART UNIT 1502 152	EXAMINER ORTIZ
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APPLICANTS

Mika Kiritani

TITLE

Semiconductor resin mold and semiconductor resin molding method
using the moldPTO-2040
12/89

ISSUING CLASSIFICATION

[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) (Date)			NOTICE OF ALLOWANCE MAILED	
				ISSUE FEE Amount Due Date Paid	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____	_____ (Primary Examiner) (Date)				
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